

Features

- · Trench LV MOSFET Technology
- ESD HBM Class 2
- · Fast Switching Speed
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

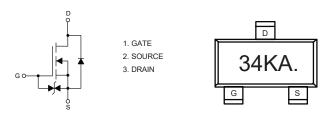
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 123°C/W Junction to Ambient(Note 2)

Parameter	Symbol	Rating	Unit		
Drain-Source Voltage	V _{DS}	20	V		
Gate-Source Volltage		V _{GS}	±12	V	
Continuous Drain Current	T _A =25°C		1.4	Α	
	T _A =70°C	- I _D	1.1		
Pulsed Drain Current ^(Note 3)		I _{DM}	5.6	Α	
Total Power Dissipation (Note 4)		P _D	1.0	W	

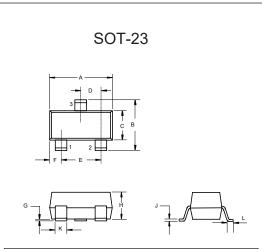
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_{D} is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code

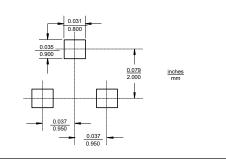


N-Channel MOSFET



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	NOTE
Α	0.110	0.120	2.80	3.04	
В	0.083	0.104	2.10	2.64	
С	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
Е	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
Н	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout





ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit	
Static Characteristics				•	,		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	20			V	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	0.9	V	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _{DS} =0V			±10	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μA	
Drain-Source On-Resistance		V _{GS} =4.5V, I _D =500mA		190	300	300	
	R _{DS(on)}	V _{GS} =2.5V, I _D =400mA 2		280	400	mΩ	
		V _{GS} =1.8V, I _D =200mA		440	700		
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =750mA		1.7		S	
Gate Resistance	R_g	f=1 MHz, Open drain		37		Ω	
Diode Characteristics							
Continuous Body Diode Current	Is				1.4	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =500mA			1.2	V	
Reverse Recovery Time	t _{rr}	I _F =500mA, dI _F /dt=100A/μs		12		ns	
Reverse Recovery Charge	Q _{rr}	1 _F =500πA, α1 _F /αι=100A/μS		0.6		nC	
Dynamic Characteristics			-				
Input Capacitance	C _{iss}			27			
Output Capacitance	C _{oss}	V _{DS} =16V,V _{GS} =0V,f=1MHz		9.3		pF	
Reverse Transfer Capacitance	C _{rss}			4.5			
Total Gate Charge	Q _g			1			
Gate-Source Charge	Q _{gs}	V _{DS} =10V,V _{GS} =4.5V,I _D =500mA		0.25		nC	
Gate-Drain Charge	Q_{gd}			0.23			
Turn-On Delay Time	t _{d(on)}			2			
Turn-On Rise Time	t _r	V _{DD} =10V,V _{GS} =10V,		17			
Turn-Off Delay Time	t _{d(off)}	$R_G=3\Omega$, $I_D=500$ mA		7		ns	
Turn-Off Fall Time	t _f			4			



Curve Characteristics

0

1

1.5

2

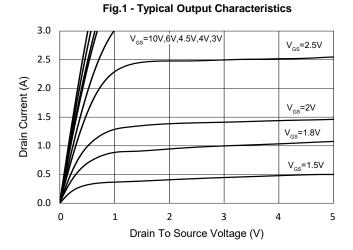
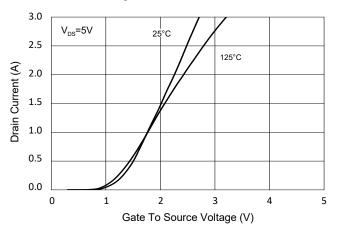


Fig.2 - Transfer Characteristic



2.5

Fig.3 - R_{DS(ON)} - V_{GS}

Fig.4 - R_{DS(ON)} - I_D

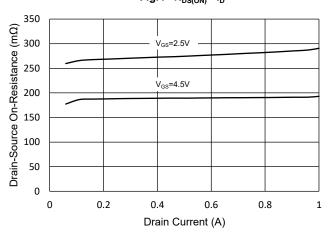


Fig.5 - Capacitance Characteristics

Gate To Source Voltage (V)

3

3.5

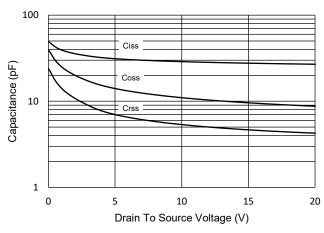
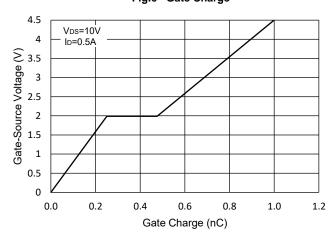


Fig.6 - Gate Charge

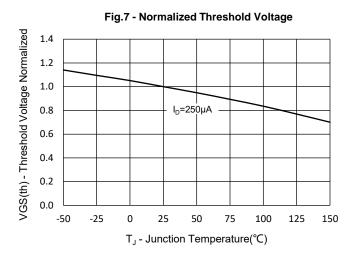


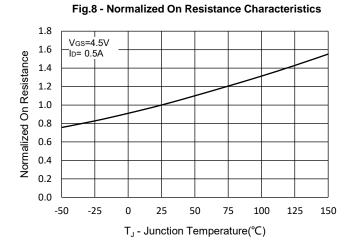
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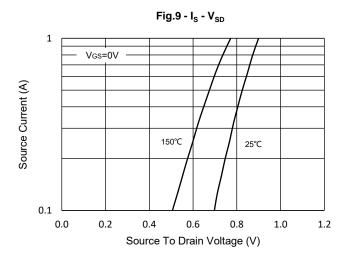
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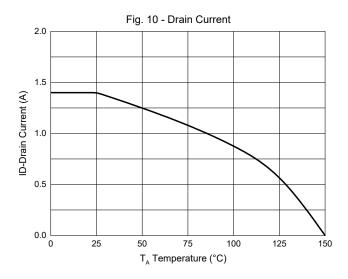


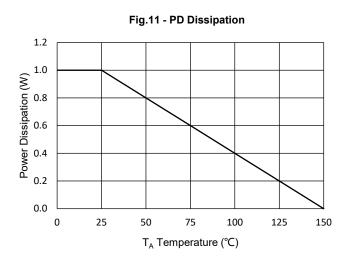
Curve Characteristics













Curve Characteristics

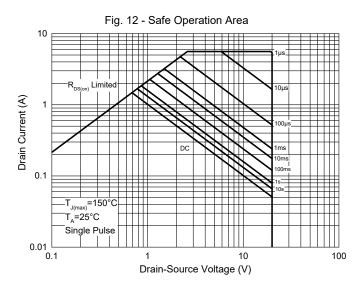
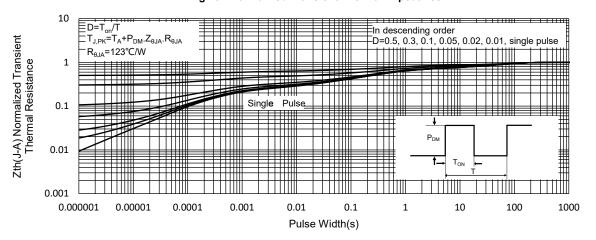


Fig.13 - Normalized Transient Thermal Impedance





Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel:3Kpcs/Reel	
Part Number-13P	Tape&Reel:10Kpcs/Reel	

For packaging details, go to our website at https://www.mccsemi.com/pdf/productpackaging/SOT-23%20Package.pdf

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